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MBRD10150CT

10A SCHOTTKY BARRIER RECTIFIER

Product Summary

MBRD10150CT	(Per Leg)		
V _{RRM} (V)	I _O (A)	V _{F (MAX)} (V) @ +25°C	I _{R (MAX)} (mA) @ +25°C
150	5	0.89	0.05

Description and Applications

This Schottky Barrier Rectifier has been designed to meet the stringent requirements of commercial applications.

- Polarity Protection Diode
- Re-Circulating Diode
- Switching Diode



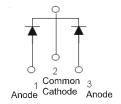
TO252 (DPAK) Top View

Features and Benefits

- Guard Ring Die Construction for Transient Protection
- High Surge Current Capability
- Low Forward Voltage Drop
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208(3)
- Polarity: See Below
- Weight: TO252 (DPAK) 0.317 grams (Approximate)



Package Pin Out Configuration

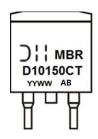
Ordering Information (Note 4)

Part Number	Case	Packaging
MBRD10150CT-13	TO252 (DPAK)	2500 pieces/tube

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



MBRD10150CT = Product Type Marking Code AB = Foundry and Assembly Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 14 = 2014) WW = Week (01 - 53)



Maximum Ratings (Per Leg) (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	150	V
Average Rectified Output Current (Per Leg) (Total)	Io	5 10	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	100	А

Thermal Characteristics (Per Leg)

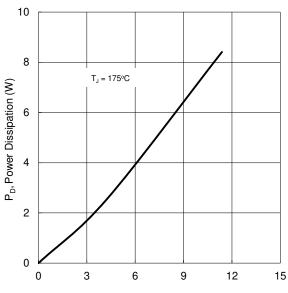
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Case (Note 5)	Rejc	6	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 5)	R ₀ JA	22	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (Per Leg) (@TA = +25°C, unless otherwise specified.)

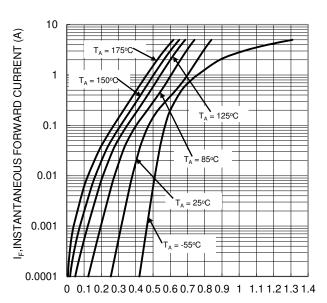
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	V_{F}		0.83 —	0.89 0.81		I _F = 5A, T _J = +25°C I _F = 5A, T _J = +125°C
Leakage Current (Note 6)	I _R		1 1	0.05 10	m A	$V_R = 150V, T_J = +25^{\circ}C$ $V_R = 150V, T_J = +125^{\circ}C$

Notes: 5. Test with 2inch Al board.

^{6.} Short duration pulse test used to minimize self-heating effect.

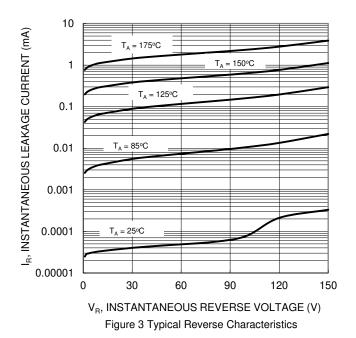


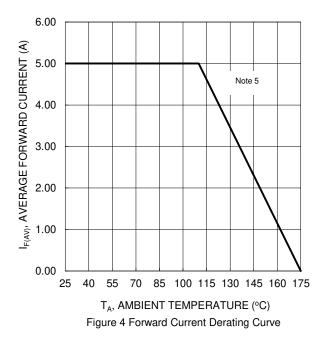
I_{F(AV)}, AVERAGE FORWARD CURRENT (A) Figure 1 Forward Power Dissipation



V_F, INSTANTANEOUS FORWARD VOLTAGE (V) Figure 2 Typical Forward Characteristics



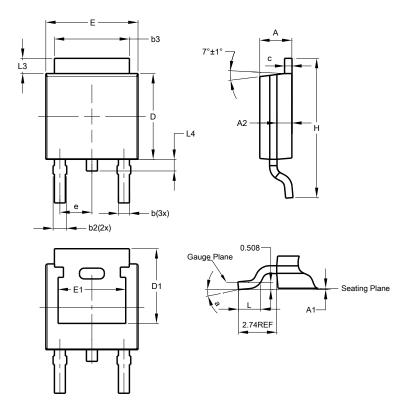




Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(1) Package Type: TO252 (DPAK)



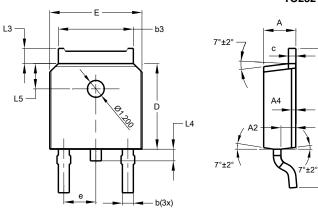
TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Ε	6.45	6.70	6.58		
E1	4.32	-	-		
H	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All	All Dimensions in mm				

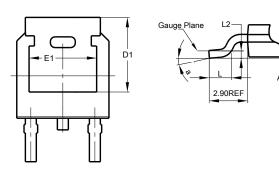


Package Outline Dimensions (Cont.)

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

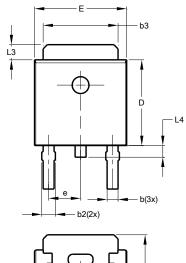
TO252 (DPAK) (Type TH)

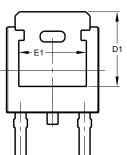


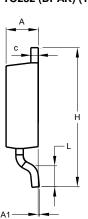


TO252 (DPAK)					
	(Type TH)				
Dim	Min Max Typ				
Α	2.20	2.38	2.30		
A 1	0.00	0.10	-		
A2	0.97	1.17	1.07		
A 4	0	.10 RE	F		
b	0.72	0.85	0.78		
b3	5.23	5.45	5.33		
С	0.47	0.58	0.53		
D	6.00	6.20	6.10		
D1	5.30 REF				
е	2.286 BSC				
Е	6.50	6.70	6.60		
E1	4.70	4.92	4.83		
Н	9.90	10.10	10.30		
L	1.40	1.70	1.60		
L2	0.51 BSC				
L3	0.90	1.25	-		
L4	0.60	1.00	0.80		
L5	1.70	1.90	1.80		
а	0°	8°	-		
All Dimensions in mm					

TO252 (DPAK) (Type BR)





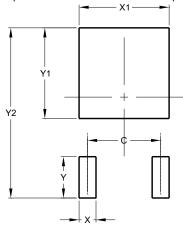


TO252 (DPAK) (Type BR)				
Dim	Min	Max	Тур	
Α	2.20	2.40	-	
A 1	0.00	0.10	-	
b	0.50	0.70	-	
b3	5.20	5.40	-	
С	0.45	0.55	-	
D	5.95	6.25	-	
D1	5.10	5.50	-	
Е	6.45	6.70	-	
E1	4.71	4.91	-	
е	2.24	2.34		
Н	9.45	9.95	-	
L	1.25	1.75	-	
L3	0.95	1.25	-	
L4	0.60	0.90	-	
All Dimensions in mm				



Suggested Pad layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	4.572		
X	1.060		
X1	5.632		
Υ	2.600		
Y1	5.700		
Y2	10.700		

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